

Refine Search

Search Results -

Terms	Documents
L4 and (nitrogen near2 plasma)	5

Database:

US Pre-Grant Publication Full-Text Database
 US Patents Full-Text Database
 US OCR Full-Text Database
 EPO Abstracts Database
 JPO Abstracts Database
 Derwent World Patents Index
 IBM Technical Disclosure Bulletins

Search:

L5

Search History

DATE: Saturday, February 21, 2004 [Printable Copy](#) [Create Case](#)

Set Name Query

side by side

Hit Count Set Name

result set

DB=USPT; PLUR=YES; OP=ADJ

<u>L5</u>	L4 and (nitrogen near2 plasma)	5	<u>L5</u>
<u>L4</u>	L3 and sidewalls and buried and (via or hole)	14	<u>L4</u>
<u>L3</u>	L2 and patterning	180	<u>L3</u>
<u>L2</u>	L1 and porous and plasma	311	<u>L2</u>
<u>L1</u>	((titanium adj nitride) or TiN) near6 (barrier)	5746	<u>L1</u>

END OF SEARCH HISTORY

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Generate OACS				

Search Results - Record(s) 1 through 5 of 5 returned.

☐ 1. Document ID: US 6566260 B2

L5: Entry 1 of 5

File: USPT

May 20, 2003

US-PAT-NO: 6566260

DOCUMENT-IDENTIFIER: US 6566260 B2

TITLE: Non-metallic barrier formations for copper damascene type interconnects

Full	Title	Citation	Front	Review	Classification	Date	Reference			Claims	KMC	Draw Dc
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☐ 2. Document ID: US 6531390 B2

L5: Entry 2 of 5

File: USPT

Mar 11, 2003

US-PAT-NO: 6531390

DOCUMENT-IDENTIFIER: US 6531390 B2

TITLE: Non-metallic barrier formations for copper damascene type interconnects

Full	Title	Citation	Front	Review	Classification	Date	Reference			Claims	KMC	Draw Dc
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☐ 3. Document ID: US 6489233 B2

L5: Entry 3 of 5

File: USPT

Dec 3, 2002

US-PAT-NO: 6489233

DOCUMENT-IDENTIFIER: US 6489233 B2

TITLE: Non-metallic barrier formations for copper damascene type interconnects

Full	Title	Citation	Front	Review	Classification	Date	Reference			Claims	KMC	Draw Dc
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☐ 4. Document ID: US 6429122 B2

L5: Entry 4 of 5

File: USPT

Aug 6, 2002

US-PAT-NO: 6429122

DOCUMENT-IDENTIFIER: US 6429122 B2

TITLE: Non metallic barrier formations for copper damascene type interconnects

Full	Title	Citation	Front	Review	Classification	Date	Reference			Claims	KMC	Draw. De
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☐ 5. Document ID: US 6284657 B1

L5: Entry 5 of 5

File: USPT

Sep 4, 2001

US-PAT-NO: 6284657

DOCUMENT-IDENTIFIER: US 6284657 B1

TITLE: Non-metallic barrier formation for copper damascene type interconnects

Full	Title	Citation	Front	Review	Classification	Date	Reference			Claims	KMC	Draw. De
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